

## ROMANIAN GOVERNMENT

### **GOVERNMENT DECISION no. 816/21.06 2006 for amending of Government Decision no. [992/2005](#) on limitation of use of certain hazardous substances in electrical and electronic equipment**

In accordance with the provision of art. 108 from Romanian Constitution, republished, Romanian Government issue the present decision:

#### **Unique article**

The Government Decision no. [992/2005](#) on limitation of use of certain hazardous substances in electrical and electronic equipment is approved and published in the Official Journal of Romania, Part I, no. 822 from September 12, 2005 with following changes and additions:

- 1.** After article 4 line (2) will be introduce new line (3) as follows:  
"(3) Annex will be changes through Common Ministerial Order with Ministry of Economy and Commerce and Ministry of Environment and Water Management, accordance with technical progress in the specific field."
- 2.** The mention about transposition of European legal acts will be as follows:  
"This Government Decision transpose the Council Directive no. 2002/95/EC, published in Official Journal of the EU no. L037/13.02.2003, the Council Decision no. 2005/618/CE which amend the Council Directive no 2002/95/CE, for the purpose of maxim values changing of certain hazardous substances in electric and electronic equipment, published in the Official Journal of the EU no. L214 from august 19, 2005, The Commission Decision no. 2005/717/CE for changing in the purpose of technical progress of Directive annex no. 2002/95/CE on the restriction of the use of certain hazardous substances in electrical and electronic equipment, published in the Official Journal of EU no. L 271 from October 15, 2005 and the commission Decision no. 2005/747/CE for changing in the technical progress purpose of annex of Directive no. 2002/95/CE on the restriction of the use of certain hazardous substances in electrical and electronic equipment, published in the Official Journal of EU no. L 280 from octber 25, 2005."
- 3.** This annex will be replaced with the annex from this Government Decision.

## ANNEX:

### **Applications of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), which are exempted from the requirements of Article 4(1) from this GD**

For the purposes of Article 5 paragraph 1 (a) from the Directive 2002/95/CE, a maximum concentration value of 0,1 % by weight in homogeneous materials for lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and of 0,01 % by weight in homogeneous materials for cadmium shall be tolerated.

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
  - halophosphate 10 mg
  - triphosphate with normal lifetime 5 mg
  - triphosphate with long lifetime 8 mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7. Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead):
  - a) lead in solders for servers, storage and storage array systems, lead in solders for network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunication,
  - b) lead in electronic ceramic parts (e.g. piezoelectronic devices).
8. Cadmium plating except for applications banned under GD 347/2003 amended, on restriction of the use of certain hazardous substances and preparation,
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
10. DecaBDE in polymeric applications
11. Lead in lead-bronze bearing shells and bushes
12. Lead used in compliant pin connector systems
13. Lead as a coating material for the thermal conduction module c-ring
14. Lead and cadmium in optical and filter glass.
15. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.
16. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.